

BC807

Rev.F Apr.-2017

/ Descriptions

SOT-23 PNP Silicon PNP transistor in a SOT-23 Plastic Package.

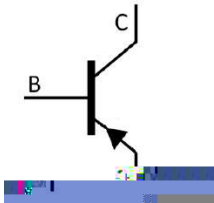
/ Features

I_C BC817
High I_C ,complementary pair with BC817.

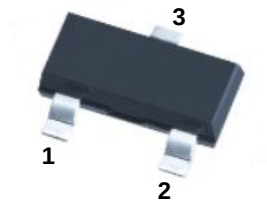
/ Applications

General power amplifier and switching applications

/ Equivalent Circuit



/ Pinning



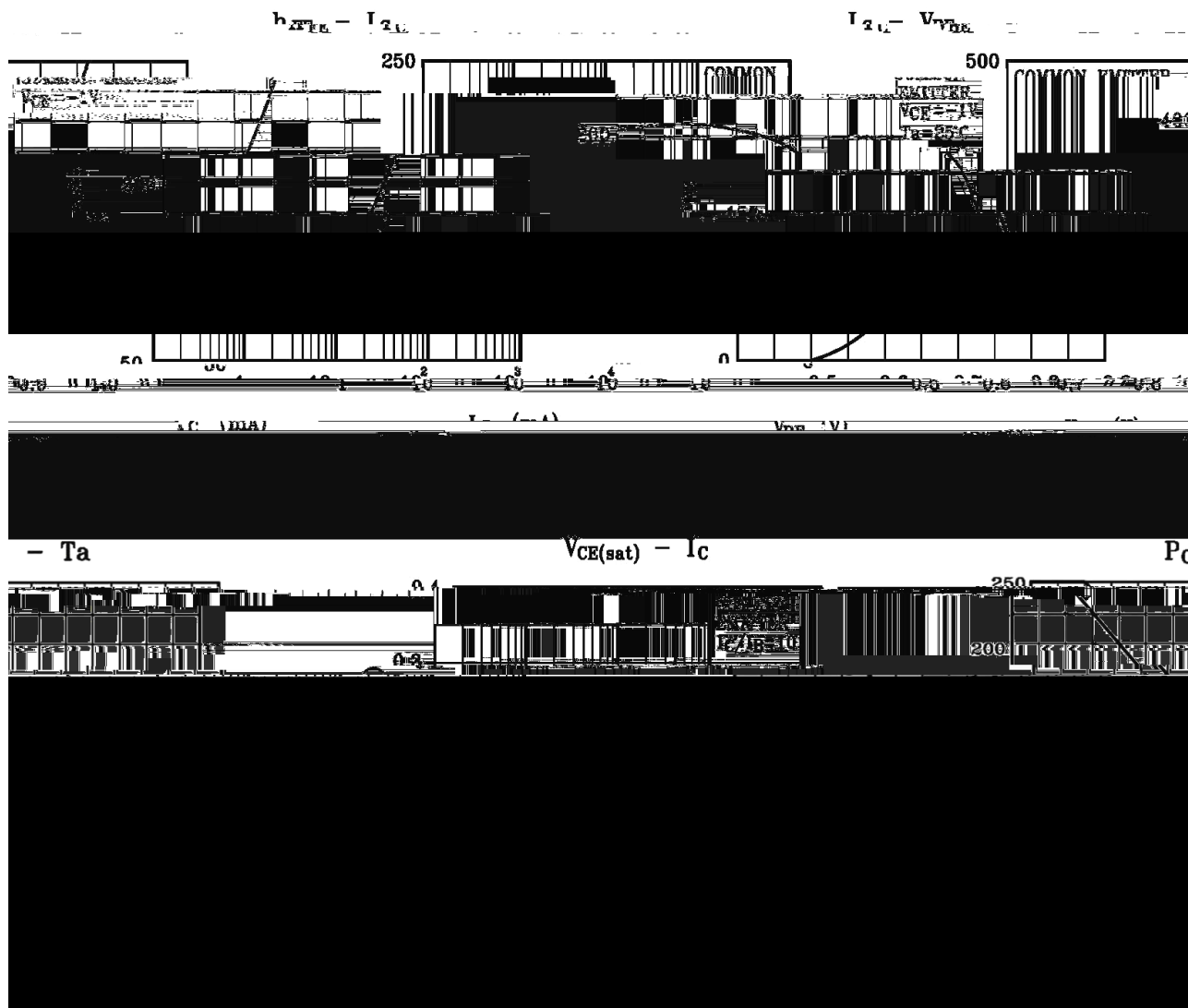
PIN1 Base PIN 2 Emitter PIN 3 Collector

/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	16	25	40
h_{FE} Range	100 250	160 400	250 600
Marking	H5A	H5B	H5C

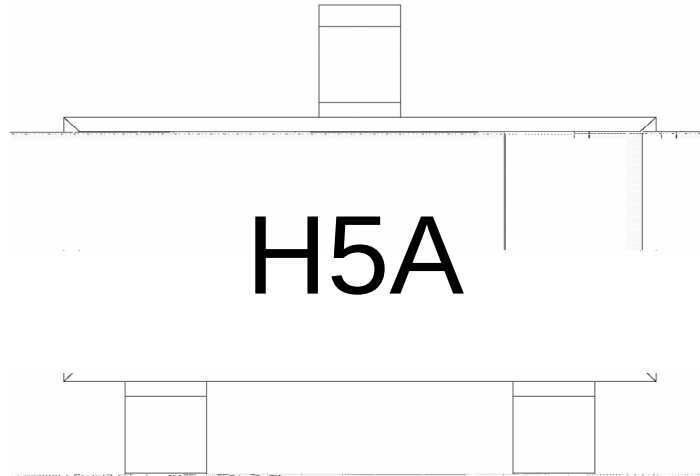
Parameter

/ Electrical Characteristic Curve



The image is a 3D architectural rendering of a building's interior structure, presented in a wireframe style. It is divided into two main horizontal sections: a blue upper section and a green lower section. The blue section shows the upper part of the building, including the roof and upper floors, with visible structural elements like beams and ductwork. The green section shows the lower part, including the ground floor and basement, with a complex network of pipes, ducts, and structural supports. The rendering is a technical drawing, likely used for architectural visualization or engineering purposes.

/ Marking Instructions



H

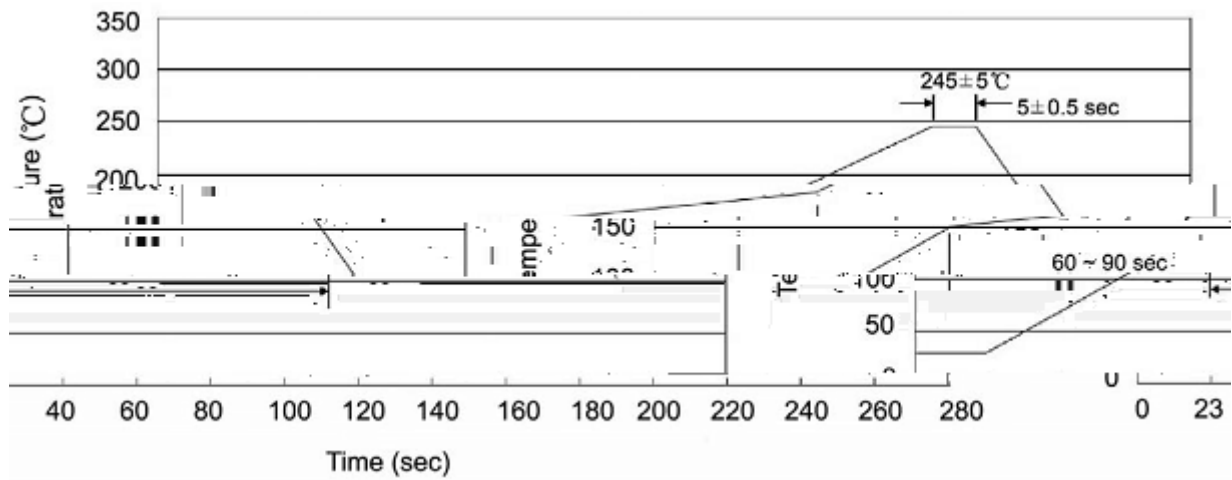
5A

Note:

H: Company Code.

5A: Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;

1.Preheating:25~150 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ Notices